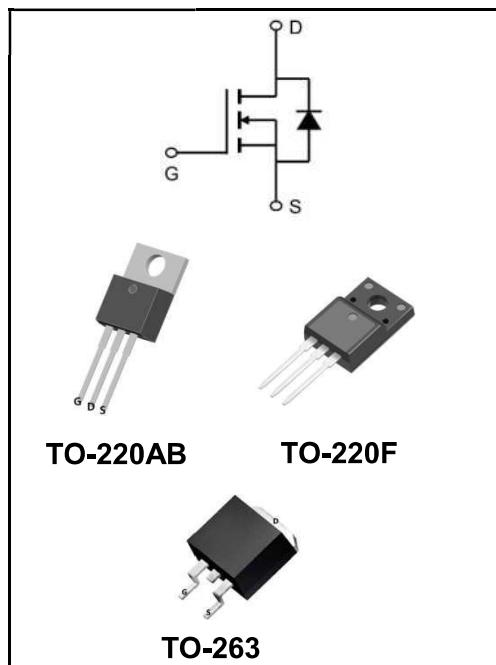


**100V N-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	120A
$V_{DSS}$	100V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 8.0mΩ (Type: 5.8 mΩ)


**Features**

- ◆ Low RDS(on) & FOM
- ◆ Extremely low switching loss
- ◆ Excellent stability and uniformity or Invertors
- ◆ YFW-SGT technology

**Application**

- ◆ Consumer electronic power supply
- ◆ Motor control
- ◆ Synchronous-rectification
- ◆ Isolated DC
- ◆ Synchronous-rectification applications

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFWG120N10AT	TO-220AB	YFW 120N10AT XXXXX	1000PCS/Box
YFWG120N10AF	TO-220F	YFW 120N10AF XXXXX	1000PCS/Box
YFWG120N10AS	TO-263	YFW 120N10AS XXXXX	800PCS/Reel

**Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified**

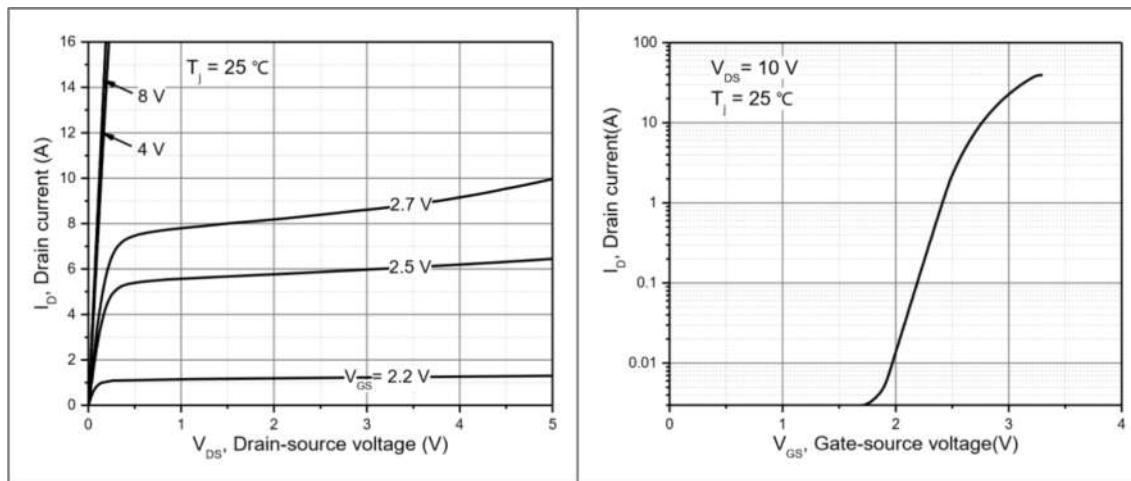
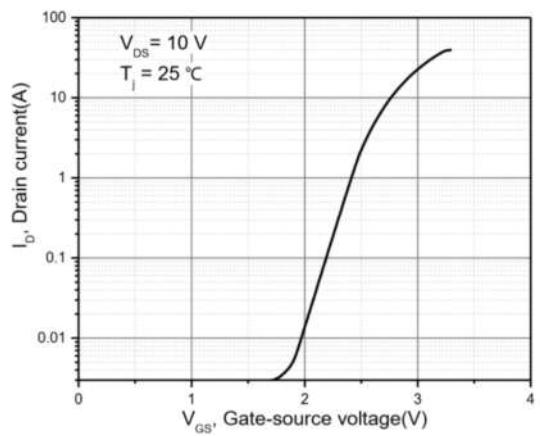
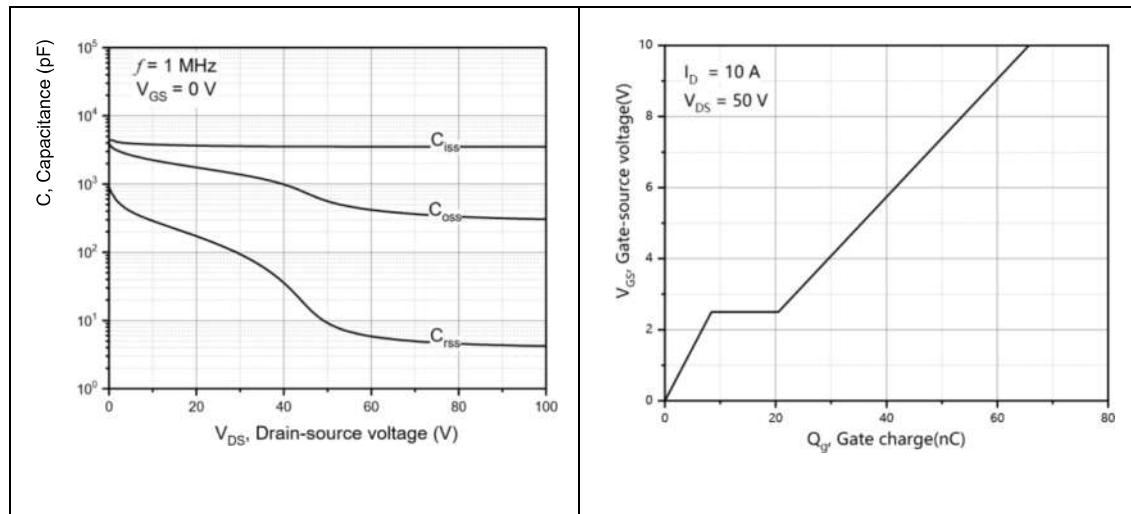
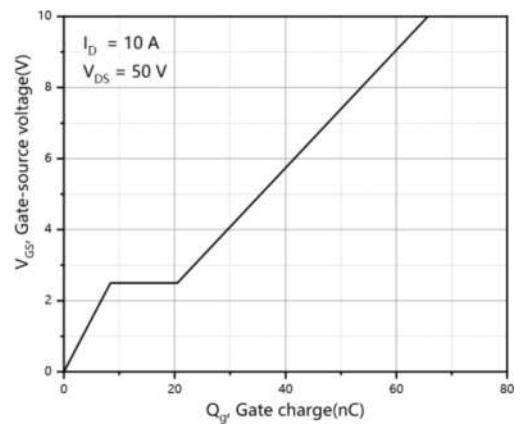
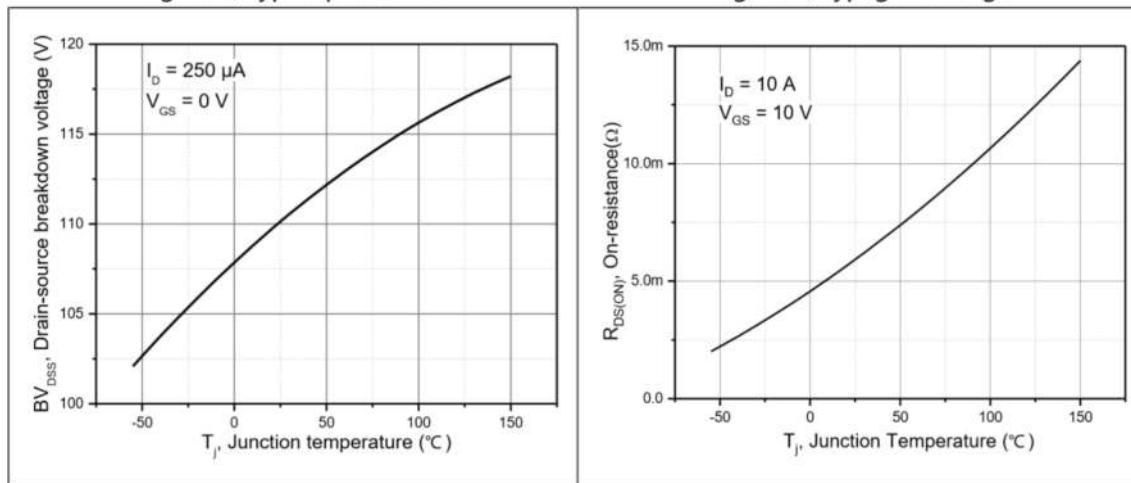
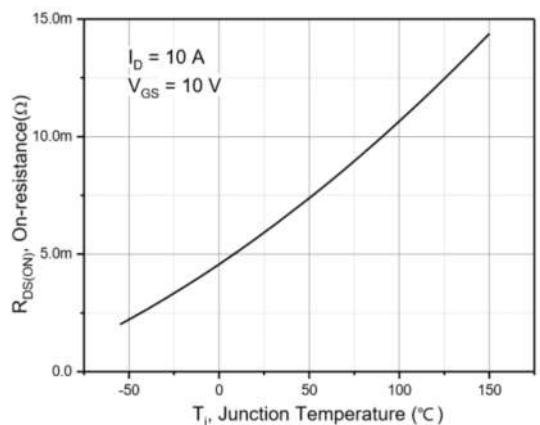
Characteristics	Symbols	Value	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current <sup>1)</sup> , $T_c=25^\circ\text{C}$	$I_D$	120	A
Pulsed drain current <sup>2)</sup> , $T_c=25^\circ\text{C}$	$I_{D, pulse}$	300	A
Power dissipation <sup>3)</sup> , $T_c=25^\circ\text{C}$	$P_D$	148	W
Single Pulse Avalanche Energy <sup>5)</sup>	$E_{AS}$	130	mJ
Operation and storage temperature	$T_{STG}, T_J$	-55 to +150	°C
Thermal Resistance, Junction-case	$R_{\theta JC}$	0.84	°C/W
Thermal Resistance, Junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62	°C/W

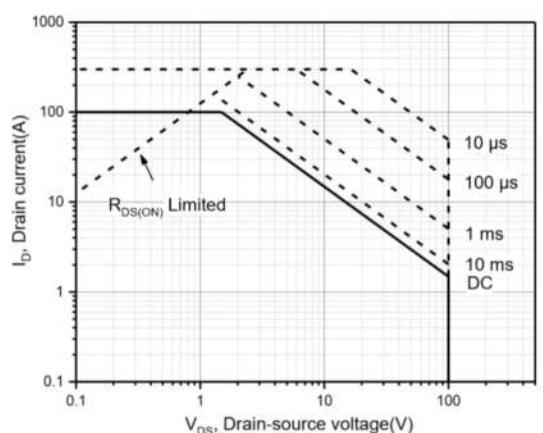
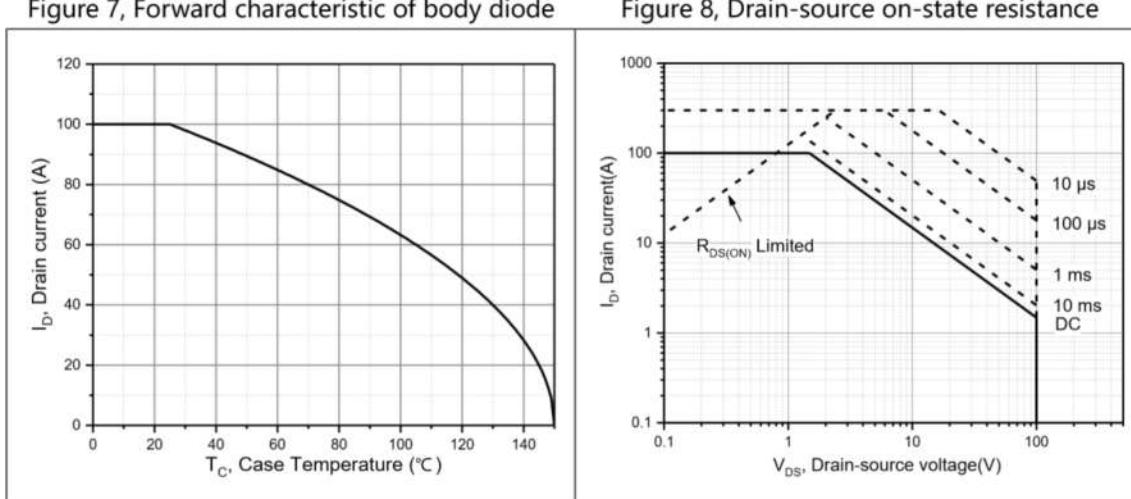
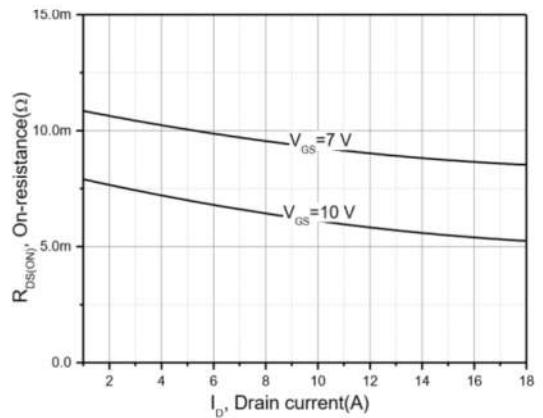
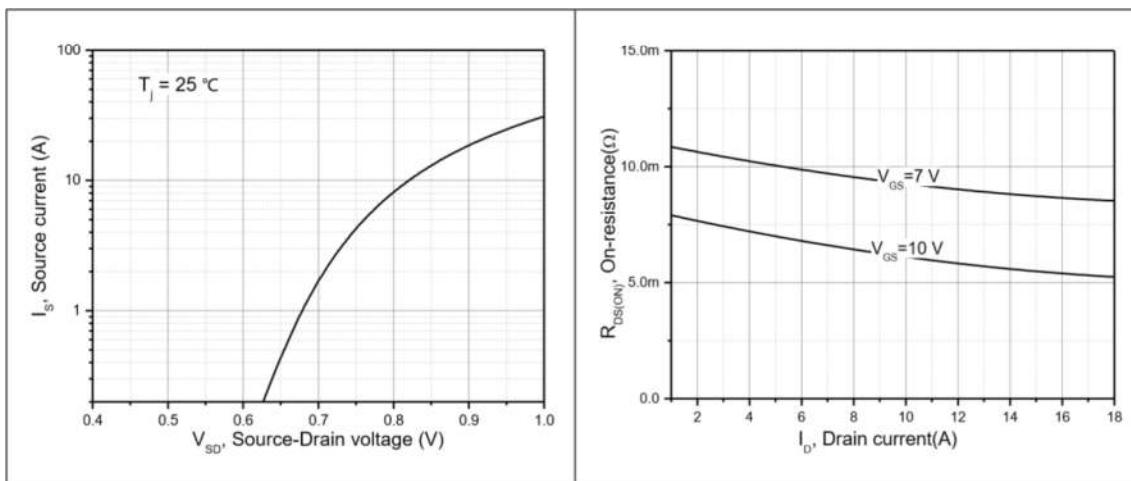
**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

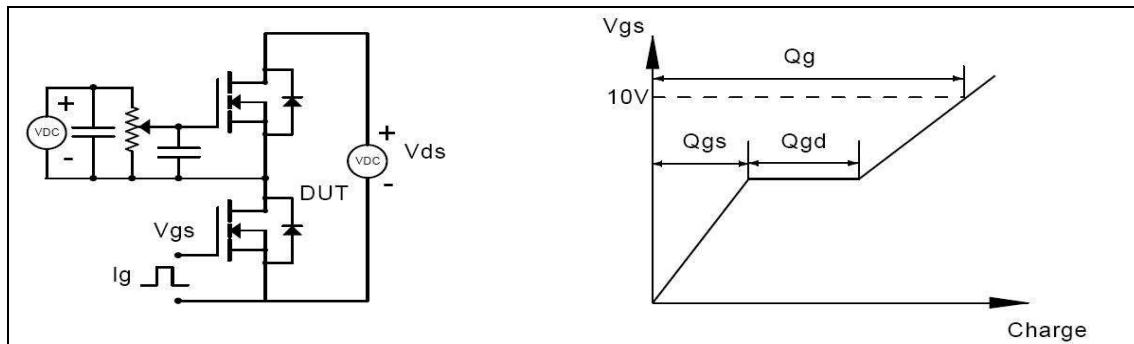
Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	BV <sub>DSS</sub>	100	-	-	V
Gate -Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	V <sub>GS(th)</sub>	2.0	-	4	V
Drain-source on-state resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =12A	R <sub>DS(ON)</sub>	-	5.8	8	mΩ
	V <sub>GS</sub> =4.5V, I <sub>D</sub> =9A		-	8.5	10	
Gate-Source Leakage Current	V <sub>GS</sub> =±20V	I <sub>GSS</sub>	-	-	±100	nA
Drain-Source Leakage Current	V <sub>DS</sub> =100V , V <sub>GS</sub> =0V	I <sub>DSS</sub>	-	-	1	μA
Input Capacitance	V <sub>GS</sub> =0V V <sub>DS</sub> =50V f=1MHz	C <sub>iss</sub>	-	3530	-	pF
Output Capacitance		C <sub>oss</sub>	-	560.1	-	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	9.0	-	
Turn-on delay time	V <sub>GS</sub> =10V V <sub>DS</sub> =50V R <sub>G</sub> =2Ω I <sub>D</sub> =10A	t <sub>d(on)</sub>	-	22.5	-	ns
Rise Time		T <sub>r</sub>	-	8.6	-	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	66.6	-	
Fall Time		t <sub>f</sub>	-	42.1	-	
Total Gate Charge	I <sub>D</sub> =10A V <sub>DS</sub> =50V V <sub>GS</sub> =10V	Q <sub>g</sub>	-	65.7	-	nC
Gate-Source Charge		Q <sub>gs</sub>	-	8.4	-	
Gate-Drain Charge		Q <sub>gd</sub>	-	12.2	-	
Gate plateau voltage		V <sub>plateau</sub>	-	2.9	-	
Diode forward current	V <sub>GS</sub> <V <sub>th</sub>	I <sub>s</sub>	-	-	100	A
Pulsed Source Current		I <sub>SP</sub>	-	-	300	A
Diode Forward Voltage	I <sub>s</sub> =30A, V <sub>GS</sub> =0 V	V <sub>SD</sub>	-	-	1.3	V
Reverse Recovery Time	I <sub>s</sub> =10A , dI/dt=100A/μs	t <sub>rr</sub>	-	67	-	ns
Reverse Recovery Charge		Q <sub>rr</sub>	-	160	-	nC
Peak reverse recovery current		I <sub>rrm</sub>	-	3.9	-	A

**■ Note**

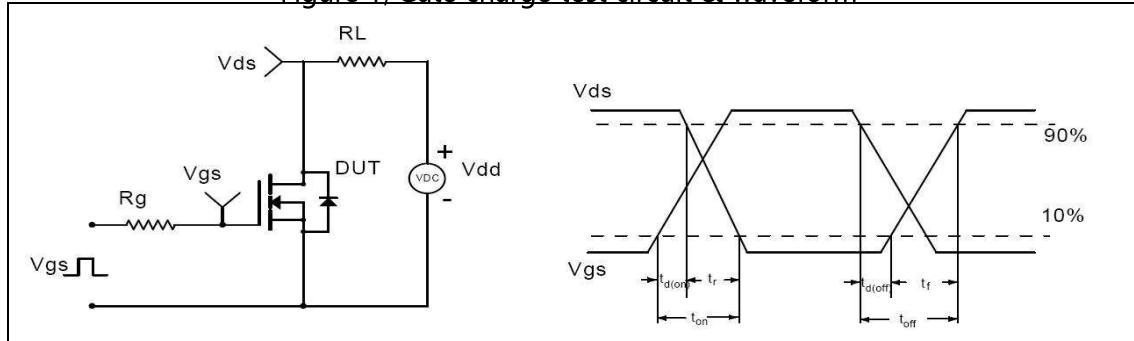
- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with Ta=25 °C.
- 5) VDD=50 V, RG=50 Ω, L=0.3 mH, starting Tj=25 °C.

**Ratings and Characteristic Curves**

**Figure 1, Typ. output characteristics**

**Figure 2, Typ. transfer characteristics**

**Figure 3, Typ. capacitances**

**Figure 4, Typ. gate charge**

**Figure 5, Drain-source breakdown voltage**

**Figure 6, Drain-source on-state resistance**

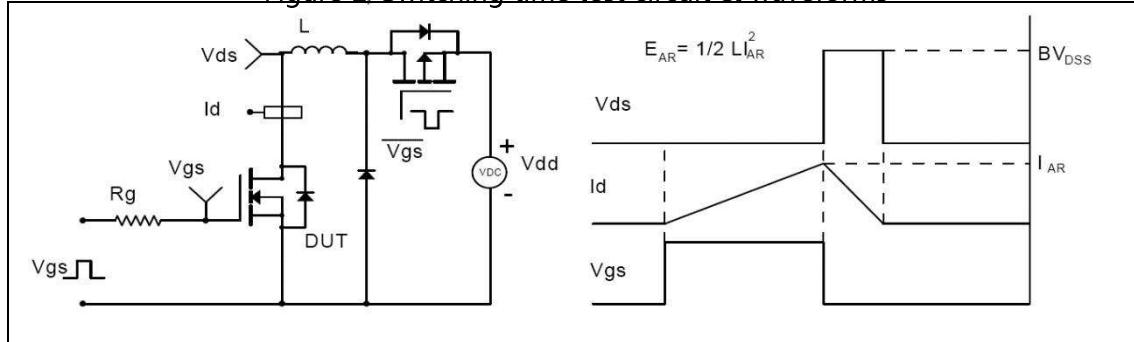
**Ratings and Characteristic Curves**


**Ratings and Characteristic Curves**
**Test circuits and waveforms**


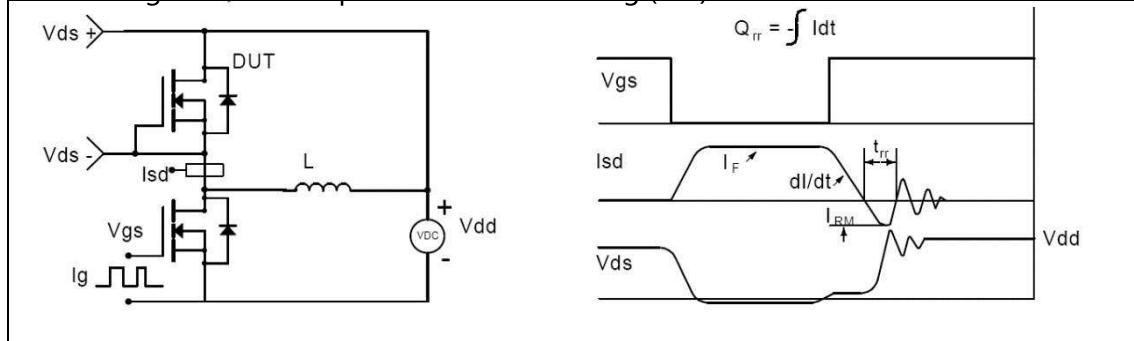
**Figure 1, Gate charge test circuit & waveform**



**Figure 2, Switching time test circuit & waveforms**



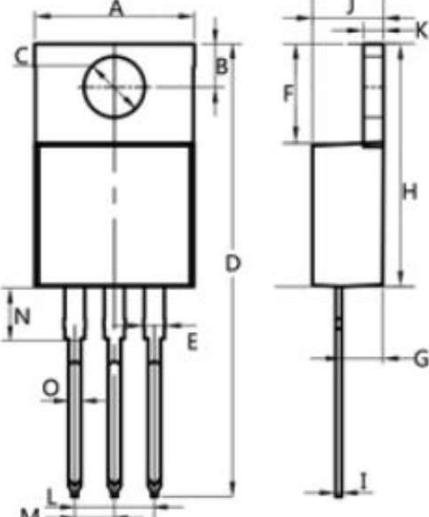
**Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4, Diode reverse recovery test circuit & waveforms**

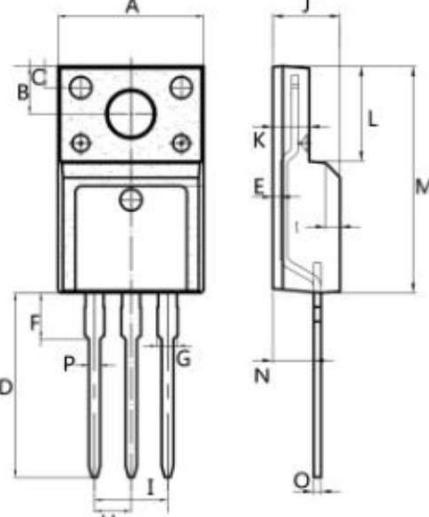
**Package Outline Dimensions Millimeters**

**TO-220AB**



Dim.	Min.	Max.
A	10.15	10.35
B	2.65	2.95
C	3.70	3.90
D	28.5	29.5
E	1.30	1.45
F	6.35	6.55
G	2.9	3.3
H	15.0	16.0
I	0.38	0.42
J	4.45	4.55
K	1.25	1.35
L	Typ 5.08	
M	Typ 2.54	
N	3.1	3.3
O	0.76	0.84
All Dimensions in millimeter		

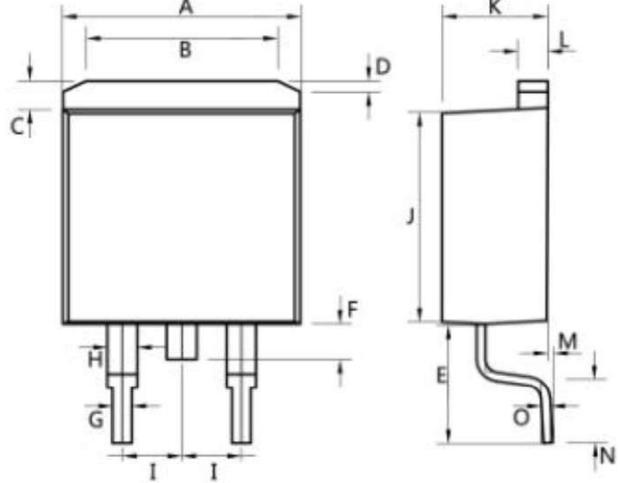
**TO-220F**



Dim.	Min.	Max.
A	9.95	10.25
B	2.95	3.25
C	1.25	1.45
D	12.95	13.25
E	0.50	0.65
F	3.1	3.3
G	1.30	1.45
H	Typ 2.54	
I	Typ 5.08	
J	4.60	4.75
K	2.50	2.65
L	6.35	6.55
M	15.4	16.0
N	2.75	3.05
O	0.48	0.52
P	0.76	0.84
All Dimensions in millimeter		

**Package Outline Dimensions Millimeters**

**TO-263**



Dim.	Min.	Max.
A	10.1	10.2
B	7.4	7.6
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.78	0.86
H	1.2	1.3
I	Typ2.54	
J	8.4	8.6
K	4.45	4.55
L	1.25	1.35
M	0.02	0.1
N	2.4	2.8
O	0.36	0.40

All Dimensions in millimeter